Semiconductor Chip Packaging With Reinforcement Frame

ABSTRACT

[0034] The present invention provides a reinforcement frame (50, 150, 200) operable for mounting onto a peripheral area around an interconnect pattern of a surface-mount semiconductor device (10) and a method of improving the solder joint reliability of a semiconductor package mountable on a printed circuit board (PCB) or circuit substrate.

[0035] FIG. 3C for publication.